



Wen Li	Fang Yang	Jiang Yang	Fang Wang





3 Charac eri ic

For ard c rren	If	30				mA
Re er e ol age	Vr	5				V
Po er di ipa ion	Pd	110				mW
Opera ing empera re range	Top	-25 +80				C
S orage empera re range	T g	-30 +80				C
Peak p l ing c rren 1/8 d f=1KH	Ifp	125				mA
Wa eleng h a peak emi ion	If=20mA	peak	620	630	635	nm
			515	520	525	
Spec ral half band id h	If=20mA			10		
For ard ol age	If=20mA	Vf	1.8	2.0	2.4	V
			3.0	3.4	3.8	
L mino in en i	If=20mA	I	500	650	800	mcd
			1000	1250	1500	
Vie ing angle a 50% IV	If=10mA		--	120	--	Deg
Re er e c rren	Vr=5V	Ir	--	--	5	A



U ef I life	-	IF=20mA	100000			H
-------------	---	---------	--------	--	--	---

Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)

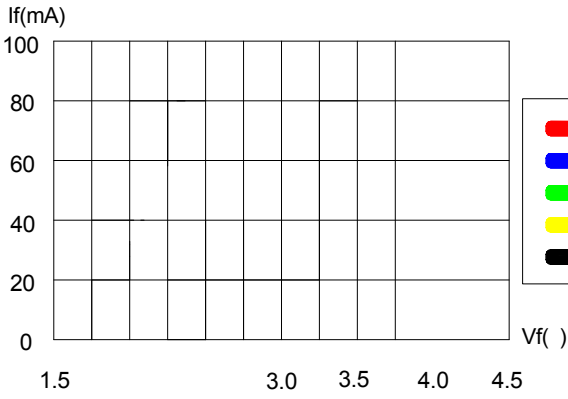


Fig.1 Forward Current vs Forward Voltage

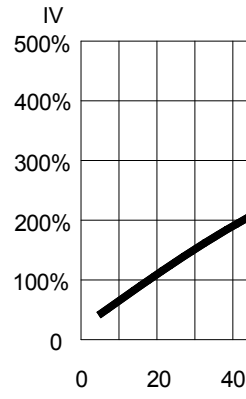


Fig.2 Relative Luminance vs Forward Current

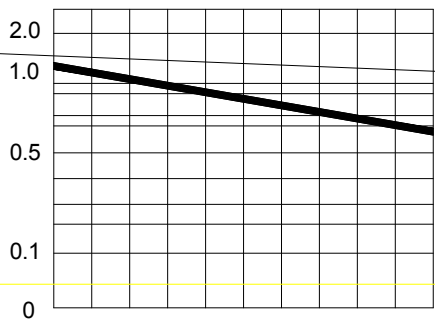


Fig.3 Relative Luminance vs Ambient Temperature

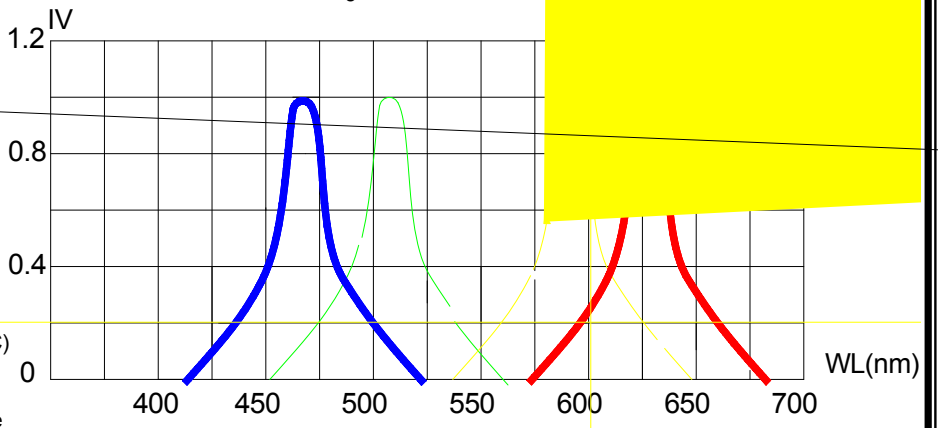


Fig.4 Relative Luminance vs Wavelength

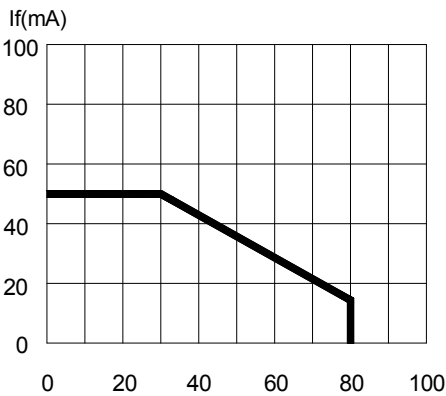
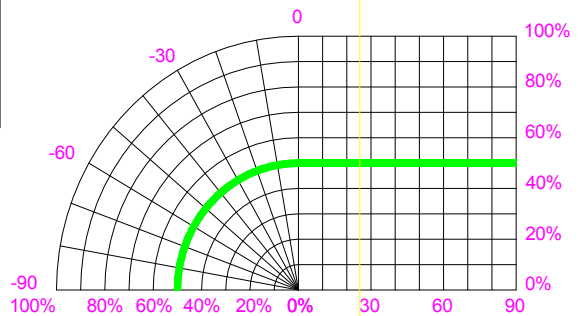


Fig.5 Maximum Forward Current vs Ambient Temperature



Direct Characteristic





1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temp alternating	High emp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heating	High emp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Test under high emp. & high humidity	85 ± 2/85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position is minimum 2mm from body.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from body.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mold must be finished by fire or professional.

iii Bracket mold must be finished before soldering.

i Bracket mold holder are connected between the pin, the distance gap of lead and the circuit board.

i. Holder be prepared in order of all the device in case of wrong polarity. Device can be closed on the heat component, working condition can repair the limit.

ii. Holder no assemble LED when the lead are deformed.

iii. When decide on assemble in hole, accuracy of hole diameter and hole distance of the line base

i. Storage in good heat positioning

i. Holder avoid any kind of quake or force on LED, before the soldering temperature return normal.

Holder be careful. When clean the body with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should be ethanol wipe, dip for no more than 3 minutes under the normal temperature.

AMZ€

